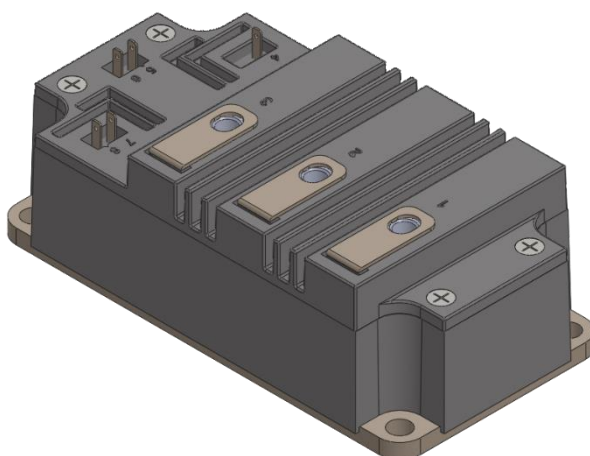


QID3320004 3300V 200A Dual HVIGBT Module



DESCRIPTION:

Powerex has expanded our HVIGBT module product line with the development of the QID3320004 3300V 200A Dual IGBT low profile module. This module makes use of the latest Mitsubishi R-Series chip technology which offers lower losses, a more rugged SWSOA and RRSOA, and a higher current handling capability as compared to the previous generations of chip technology.

Highly insulated housings offer enhanced protection by means of greater creepage and strike clearance distance for many demanding applications like medium voltage drives and auxiliary traction.

All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

FEATURES:

- Advanced Mitsubishi R-Series Chip Technology
- UL Recognized (E78240)
- Low $V_{CE(sat)}$
- Creepage and Clearance meet IEC 60077-1
- High Isolation Voltage: 9.0kV_{RMS}
- Rugged SWSOA and RRSOA
- Compact Industry Standard Package
- Cu Baseplate

APPLICATIONS:

- Medium Voltage Drives
- High Voltage Power Supplies

Package Configuration:

QID3320004

